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Date: March 10, 2004

June M. Keating

PATENT
36856.1170

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Eiichi NAGATSUKA et al.	Art Unit: 1725
Serial No.: 10/712,034	
Filed: November 14, 2003	Examiner: unknown
Title: RESISTANCE WELDING METHOD AND STRUCTURE OF RESISTANCE WELDING PART, AND METHOD FOR MANUFACTURING ELECTRONIC COMPONENT AND ELECTRONIC COMPONENT	

INFORMATION DISCLOSURE STATEMENT

Mail Stop DD
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

Pursuant to 37 C.F.R. § 1.56, submitted herewith are copies of four (4) references cited in the enclosed Office Action issued in a corresponding Japanese Patent Application. For the Examiner's convenience, we have enclosed an English translation of the Japanese Office Action from the corresponding Japanese Patent Application and a completed Form PTO-1449.

The relevance of JP 63-165835 is set forth in the English translation of the Japanese Search Report attached hereto. Further, although the Japanese Search Report cites JP 3-258467, applicants did not include a copy of the reference herewith as

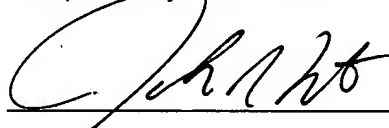
the reference has been previously cited in an Information Disclosure Statement filed on November 14, 2003.

The statement is not a representation that all of the information cited is necessarily effective as prior art against the application.

I hereby state that each item of information contained in this Information Disclosure Statement was cited in a communication from a foreign patent office in a counterpart foreign application not more than 3 months prior to the filing of this statement, and that this is the first citation of these prior art references by a foreign patent office in a counterpart foreign patent application. Accordingly, no fee is necessary for the filing of this statement. Should the Commissioner determine otherwise, the Commissioner is authorized to charge Deposit Account No. 50-1353 for any fee shortages, including the petition fee under 37 C.F.R. § 1.17(p).

Applicants respectfully request that the disclosed references be made of record in the subject application.

Respectfully submitted,



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Date: March 10, 2004

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NOTIFICATION OF REASONS FOR REJECTION

Patent Application No.: Patent Application No. 248164 of Heisei 11 [1999]
Draft Date: January 30, 2004
Patent Office Examiner: Toshiro Kanazawa 3117 3P00
Agent of Patent Applicant: Masaaki Koshiba (and one other)
Applicable Sections: Section 29 (2)

[Stamp: Received, 2/12/04, Koshiba Patent Office]

The present application should be rejected for the following reasons. If you have an opinion concerning this, please submit a statement of opinion within 60 days of the date of dispatch of this notification.

Reasons

The inventions claimed in the following claims of the present application are inventions that could easily have been invented prior to the filing of the application by a person having an ordinary knowledge of the technical field to which the inventions belong on the basis of inventions described in the following publications, which were disseminated in Japan or in foreign countries prior to the filing of the application. Thus, in accordance with the provisions of Section 29 (2) of the Patent Law, these inventions cannot be patented.

Note (For cited references, etc., see the Table of Cited References, etc.)

- Claims 1 through 3 and 5 through 10
- Cited References, etc. 1, 2, and 3
- Remarks:

In Cited Reference 1, see Claims 1 and 2, etc.

In Cited Reference 2, see Embodiment 1.

In Cited Reference 3, see the fact that metal gaps [*sic*]* 12 and 13 consisting of silver-plated iron and center conductors 8 consisting of phosphor bronze are resistance-welded.

No particular difference is recognized between the invention described in Cited Reference 1 or 2 and the inventions of Claims 1 through 3 and 5 of the present application.

The invention of Claim 6 of the present application specifies the thickness of the alloy layer, but the optimization of the numerical range of the thickness of the alloy layer is not recognized as something that goes beyond the ordinary creative ability range exhibited by a person skilled in the art.

A person skilled in the art could easily envision the use of nickel plating (Cited References 1

[Stamp: 2/13/04, Otaru]

* Translator's note: apparent error in the original for "metal caps."

and 2) that is universally known in the resistance welding of an iron-type alloy and a copper-type alloy, in place of silver plating described in Cited Reference 3, thus devising the inventions of Claims 7 through 10 of the present application.

- Claim 4
- Cited References, etc. 4 and 5
- Remarks:

In Cited Reference 4, see Claim 2.

In Cited Reference 5, see the description in line 5 of the upper-right section of page 2 to line 7 of the lower-right section of the same page.

It is recognized that the Fe-Sn-type alloy layer growth problem is also encountered in the invention described in Cited Reference 4, in which iron or an iron alloy is plated with tin. A person skilled in the art could envision without any particular difficulty the invention of Claim 4 of the present application by referring to the invention described in Cited Reference 5, which belongs to the same technical field of resistance welding and which suppresses the growth of an Fe-Sn-type alloy layer in the resistance welding using a nickel-plated underlying layer so that welding defects are not generated, and by adding a nickel-plated underlying layer.

Furthermore,

- 1) If amending the specification, underline the portions of the description where changes are made as a result of the amendment. (Regulation under the Patent Law, Format No. 13, Remark 6)
- 2) When making amendment(s), care should be taken not to add a new item, and the portions of the description constituting the grounds for the amendment(s) in the initial specification at the time of filing should be indicated in an Opinion Brief.

Table of Cited References, etc.

1. Japanese Patent Application Kokai No. H03-258467
2. Japanese Patent Application Kokai No. H02-256158
3. Microfilm of Japanese Utility Model Application No. S62-058143 (Japanese Utility Model Application Kokai No. S63-165835)
4. Japanese Patent Application Kokai No. H04-089180
5. Japanese Patent Application Kokai No. S57-023091

Record of Results of Survey of Prior Art References

- Field surveyed: IPC 7th Edition B23K 11/12
- Prior Art References: Japanese Patent Application Kokai No. H04-251679 (Claim 5, Table 4, etc.)

File No. 199086

Dispatch No. 037451 3/E

Dispatch Date: February 10, 2004

This record of the results of a survey of prior art references does not constitute any reason for rejection.

If you have any inquiries regarding the content of this Notification of Reasons for Rejection, or if you wish to have an interview, please contact [the following person]:

Examination Department 2, Special Processing, Tatsushi Onoda
TEL. 03 (3581) 1101, extension 3364

